

**400 mA LOAD SWITCH FEATURING PRE-BIASED PNP TRANSISTOR AND ESD PROTECTED N-MOSFET**

NEW PRODUCT

**General Description**

LMN400E01 is best suited for applications where the load needs to be turned on and off using control circuits like micro-controllers, comparators etc. particularly at a point of load. It features a discrete pass transistor with stable  $V_{CE(SAT)}$  which does not depend on input voltage and can support continuous maximum current of 400 mA. It also contains an ESD protected discrete N-MOSFET that can be used as control. The component can be used as a part of a circuit or as a stand alone discrete device.

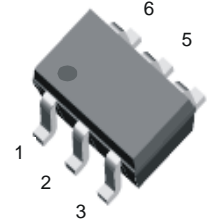


Fig. 1: SOT-363

**Features**

- Voltage Controlled Small Signal Switch
- N-MOSFET with ESD Gate Protection
- Surface Mount Package
- Ideally Suited for Automated Assembly Processes
- **Lead Free By Design/ROHS Compliant (Note 1)**
- **"Green" Device (Note 2)**

**Mechanical Data**

- Case: SOT-363
- Case Material: Molded Plastic. "Green Molding" Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminal Connections: See Diagram
- Terminals: Finish - Matte Tin annealed over Alloy 42 leadframe. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 8
- Ordering Information: See Page 8
- Weight: 0.006 grams (approximate)

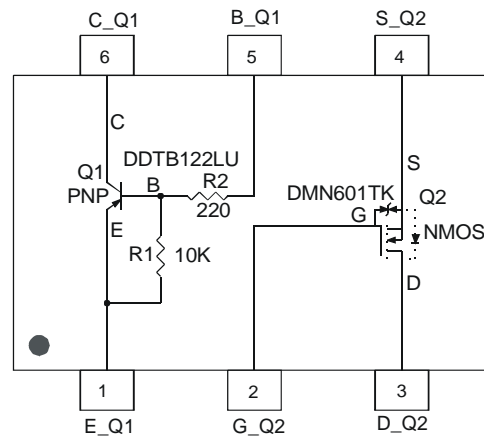


Fig 2: Schematic and Pin Configuration

Sub-Component P/N	Reference	Device Type	R1(NOM)	R2(NOM)	Figure
DDTB122LU_DIE	Q1	PNP Transistor	10K	220	2
DMN601TK_DIE (ESD Protected)	Q2	N-MOSFET	—	—	2

**Maximum Ratings, Total Device** @ $T_A = 25^\circ\text{C}$  unless otherwise specified

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 3)	$P_D$	200	mW
Power Derating Factor above $37.5^\circ\text{C}$	$P_{der}$	1.6	mW/ $^\circ\text{C}$
Output Current	$I_{out}$	400	mA

**Thermal Characteristics** @ $T_A = 25^\circ\text{C}$  unless otherwise specified

Characteristic	Symbol	Value	Unit
Junction Operation and Storage Temperature Range	$T_j, T_{STG}$	-55 to +150	$^\circ\text{C}$
Thermal Resistance, Junction to Ambient Air (Equivalent to one heated junction of PNP transistor) (Note 3)	$R_{\theta JA}$	625	$^\circ\text{C/W}$

- Notes:
1. No purposefully added lead.
  2. Diodes Inc.'s "Green" policy can be found on our website at [http://www.diodes.com/products/lead\\_free/index.php](http://www.diodes.com/products/lead_free/index.php).
  3. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.

**Maximum Ratings:**
**Sub-Component Device: Pre-Biased PNP Transistor (Q1)** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-50	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-50	V
Supply Voltage	V <sub>CC</sub>	-50	V
Input Voltage	V <sub>in</sub>	+5 to -6	V
Output Current	I <sub>C</sub>	-400	mA

**Sub-Component Device:**
**ESD Protected N-Channel MOSFET (Q2)** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DSS</sub>	60	V
Drain Gate Voltage (R <sub>GS</sub> ≤ 1M Ohm)	V <sub>DGR</sub>	60	V
Gate-Source Voltage	V <sub>GSS</sub>	Continuous	+/-20
		Pulsed (tp < 50 uS)	+/-40
Drain Current (Page 1: Note 3)	I <sub>D</sub>	Continuous (V <sub>gs</sub> = 10V)	300
		Pulsed (tp < 10 uS, Duty Cycle < 1%)	800
Continuous Source Current	I <sub>S</sub>	300	mA

**Electrical Characteristics: Pre-Biased PNP Transistor (Q1)** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 4)</b>						
Collector-Base Cut Off Current	I <sub>CBO</sub>	—	—	-100	nA	V <sub>CB</sub> = -50V, I <sub>E</sub> = 0
Collector-Emitter Cut Off Current	I <sub>CEO</sub>	—	—	-500	nA	V <sub>CE</sub> = -50V, I <sub>B</sub> = 0
Emitter-Base Cut Off Current	I <sub>EBO</sub>	—	—	-1	mA	V <sub>EB</sub> = -5V, I <sub>C</sub> = 0
Collector-Base Breakdown Voltage	V <sub>(BR)CBO</sub>	-50	—	—	V	I <sub>C</sub> = -10uA, I <sub>E</sub> = 0
Collector-Emitter Breakdown Voltage	V <sub>(BR)CEO</sub>	-50	—	—	V	I <sub>C</sub> = -2mA, I <sub>B</sub> = 0
Input Off Voltage	V <sub>I(OFF)</sub>	—	-0.55	-0.3	V	V <sub>CE</sub> = -5V, I <sub>C</sub> = -100uA
Output Voltage	V <sub>OH</sub>	-4.9	—	—	V	V <sub>CC</sub> = -5V, V <sub>B</sub> = -0.05V, R <sub>L</sub> = 1K
Output Current (leakage current same as I <sub>CEO</sub> )	I <sub>O(OFF)</sub>	—	—	-500	nA	V <sub>CC</sub> = -50V, V <sub>I</sub> = 0V
<b>ON CHARACTERISTICS (Note 4)</b>						
Collector-Emitter Saturation Voltage	V <sub>CE(SAT)</sub>	—	—	-0.15	V	I <sub>C</sub> = -10mA, I <sub>B</sub> = -0.3mA
		—	—	-0.3	V	I <sub>C</sub> = -200mA, I <sub>B</sub> = -20mA
		—	—	-0.5	V	I <sub>C</sub> = -400mA, I <sub>B</sub> = -40mA
		—	—	-0.6	V	I <sub>C</sub> = -500mA, I <sub>B</sub> = -50mA
Equivalent on-resistance	R <sub>CE(SAT)</sub>	—	—	1.125	Ω	I <sub>C</sub> = -400mA, I <sub>B</sub> = -40mA
DC Current Gain	h <sub>FE</sub>	70	220	—	—	V <sub>CE</sub> = -5V, I <sub>C</sub> = -50mA
		70	225	—	—	V <sub>CE</sub> = -5V, I <sub>C</sub> = -400mA
Input On Voltage	V <sub>I(ON)</sub>	-3	-1.5	—	V	V <sub>O</sub> = -0.3V, I <sub>C</sub> = -20mA
Output Voltage (Equivalent to V <sub>CE(SAT)</sub> )	V <sub>O(ON)</sub>	—	-0.1	-0.3	V	I <sub>O</sub> /I <sub>I</sub> = -50mA / -2.5mA
Input Current	I <sub>I</sub>	—	-18	-28	mA	V <sub>I</sub> = -5V
Base-Emitter Turn-on Voltage	V <sub>BE(ON)</sub>	—	-1.2	-1.4	V	V <sub>CE</sub> = -5V, I <sub>C</sub> = -400mA
Base-Emitter Saturation Voltage	V <sub>BE(SAT)</sub>	—	-1.9	-2.2	V	I <sub>C</sub> = -50mA, I <sub>B</sub> = -5mA
Input Resistor (Base), +/- 30%	R2	0.154	0.22	0.286	KΩ	—
Pull-up Resistor (Base to V <sub>CC</sub> supply), +/- 30%	R1	7	10	13	KΩ	—
Resistor Ratio (Input Resistor/Pullup resistor)	R1/R2	36	45	55	—	—
<b>SMALL SIGNAL CHARACTERISTICS</b>						
Transition Frequency (Gain Bandwidth Product)	f <sub>T</sub>	—	200	—	MHz	V <sub>CE</sub> = -10V, I <sub>E</sub> = -5mA, f = 100MHz
Collector capacitance, (C <sub>cb0</sub> -Output Capacitance)	CC	—	20	—	pF	V <sub>CB</sub> = -10V, I <sub>E</sub> = 0A, f = 1MHz

Notes: 4. Short duration pulse test used to minimize self-heating effect.

## Electrical Characteristics: ESD Protected N-Channel MOSFET (Q2) @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 4)</b>						
Drain-Source Breakdown Voltage, $BV_{dss}$	$V_{(BR)DSS}$	60	—	—	V	$V_{GS} = 0V, I_D = 10\mu A$
Zero Gate Voltage Drain Current (Drain Leakage Current)	$I_{DSS}$	—	—	1	$\mu A$	$V_{GS} = 0V, V_{DS} = 60V$
Gate-Body Leakage Current, Forward	$I_{GSSF}$	—	—	10	$\mu A$	$V_{GS} = 20V, V_{DS} = 0V$
Gate-Body Leakage Current, Reverse	$I_{GSSR}$	—	—	-10	$\mu A$	$V_{GS} = -20V, V_{DS} = 0V$
<b>ON CHARACTERISTICS (Note 4)</b>						
Gate Source Threshold Voltage (Control Supply Voltage)	$V_{GS(th)}$	1	1.6	2.5	V	$V_{DS} = V_{GS}, I_D = 0.25mA$
Static Drain-Source On-State Voltage	$V_{DS(on)}$	—	0.09	1.5	V	$V_{GS} = 5V, I_D = 50mA$
		—	0.6	3.75		$V_{GS} = 10V, I_D = 500mA$
On-State Drain Current	$I_{D(on)}$	500	—	—	mA	$V_{GS} = 10V,$ $V_{DS} \geq 2 \cdot V_{DS(ON)}$
Static Drain-Source On Resistance	$R_{DS(on)}$	—	1.6	3	$\Omega$	$V_{GS} = 5V, I_D = 50mA$
		—	1.2	2		$V_{GS} = 10V, I_D = 500mA$
Forward Transconductance	$g_{FS}$	80	260	—	mS	$V_{DS} \geq 2 \cdot V_{DS(ON)}, I_D = 200mA$
<b>DYNAMIC CHARACTERISTICS</b>						
Input Capacitance	$C_{iss}$	—	—	50	pF	$V_{DS} = -25V, V_{GS} = 0V, f = 1MHz$
Output Capacitance	$C_{oss}$	—	—	25	pF	
Reverse Transfer Capacitance	$C_{rss}$	—	—	5	pF	
<b>SWITCHING CHARACTERISTICS (Note 4)</b>						
Turn-On Delay Time	$t_{d(on)}$	—	—	20	ns	$V_{DD} = 30V, V_{GS} = 10V,$ $I_D = 200mA,$ $R_G = 25\text{ Ohm}, R_L = 150\text{ Ohm}$
Turn-Off Delay Time	$t_{d(off)}$	—	—	40	ns	
<b>SOURCE-DRAIN (BODY) DIODE CHARACTERISTICS AND MAXIMUM RATINGS</b>						
Drain-Source Diode Forward On-Voltage	$V_{SD}$	—	0.88	1.5	V	$V_{GS} = 0V, I_S = 300mA^*$
Maximum Continuous Drain-Source Diode Forward Current (Reverse Drain Current)	$I_S$	—	—	300	mA	
Maximum Pulsed Drain-Source Diode Forward Current	$I_{SM}$	—	—	800	mA	

### Typical Characteristics

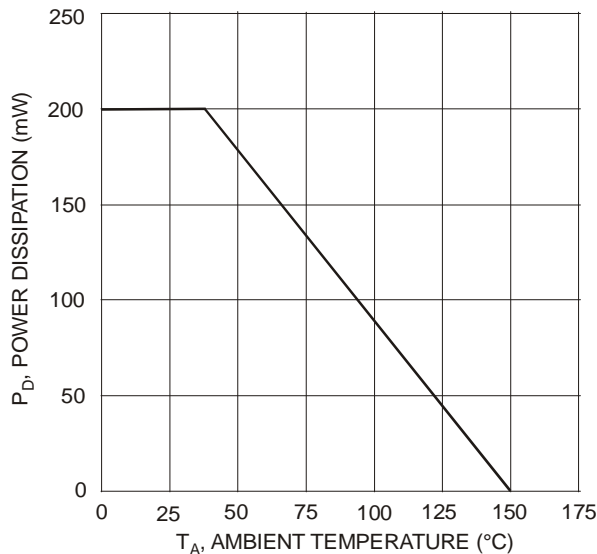


Fig. 3 Max Power Dissipation vs. Ambient Temperature

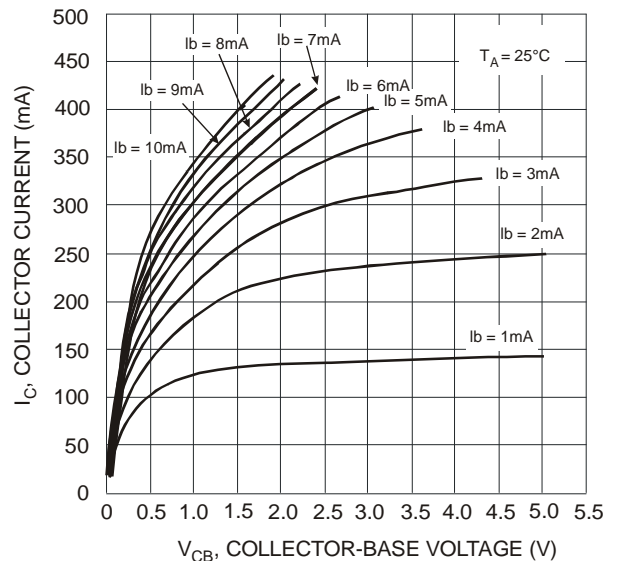


Fig. 4 Output Current vs. Voltage Drop (Pass Element PNP)

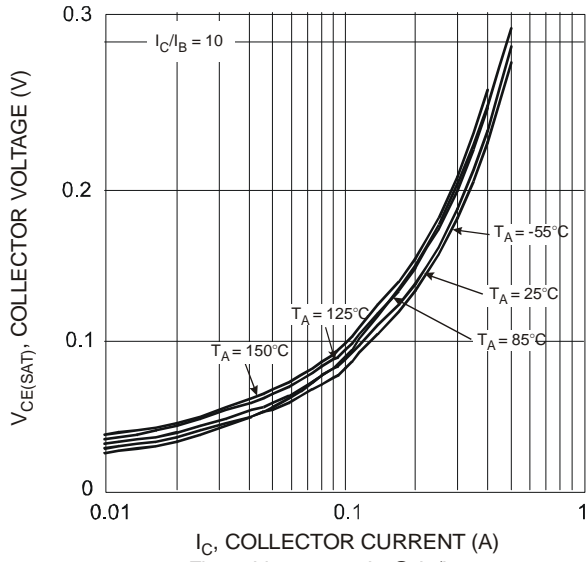


Fig. 5  $V_{CE(SAT)}$  vs.  $I_C$  @  $I_C/I_B = 10$

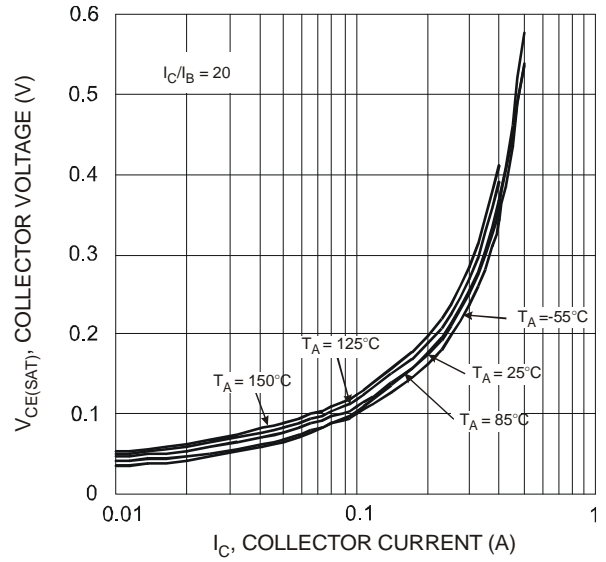


Fig. 6  $V_{CE(SAT)}$  vs.  $I_C$  @  $I_C/I_B = 20$

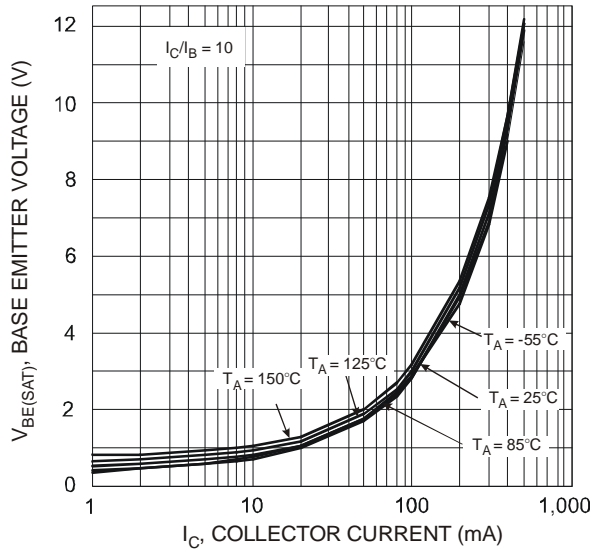


Fig. 7  $V_{BE(SAT)}$  vs.  $I_C$  @  $I_C/I_B = 10$

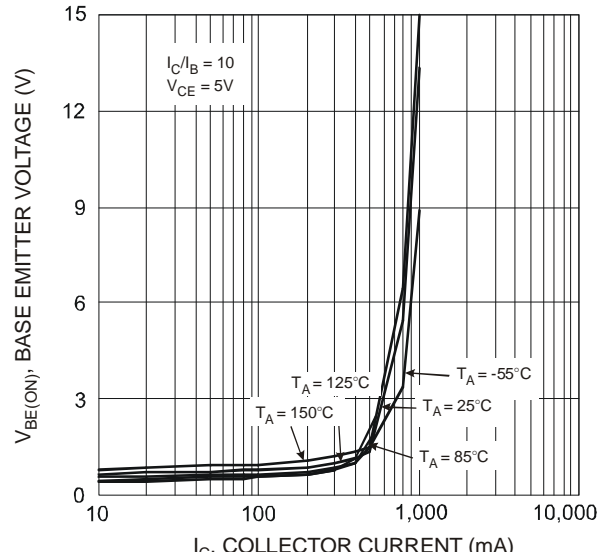


Fig. 8  $V_{BE(ON)}$  vs.  $I_C$  @  $V_{CE} = 5\text{V}$

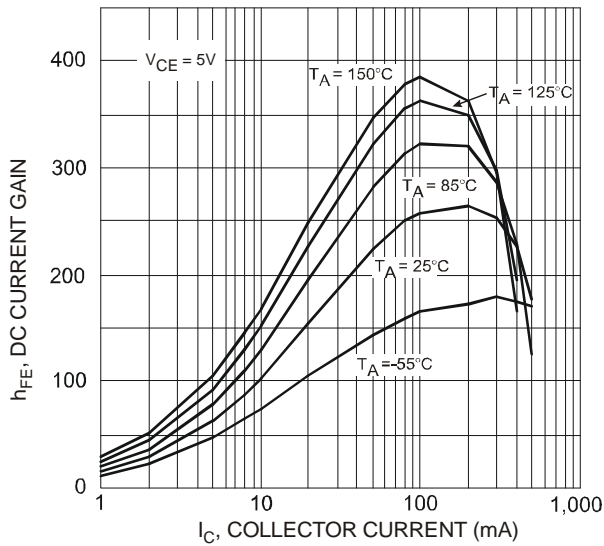
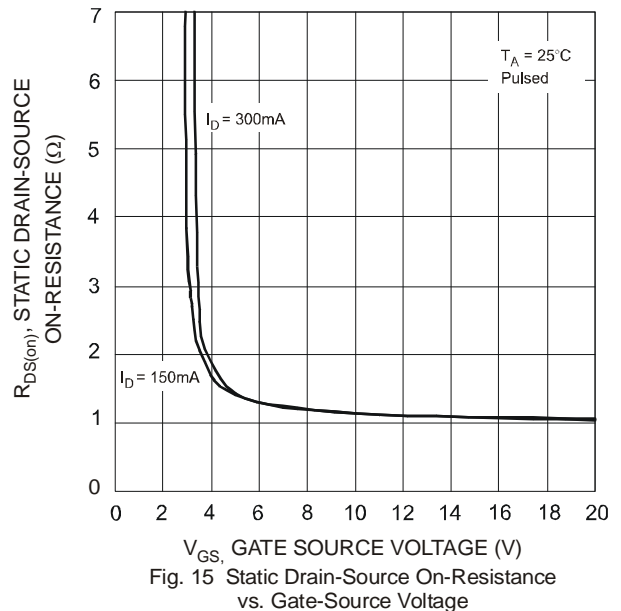
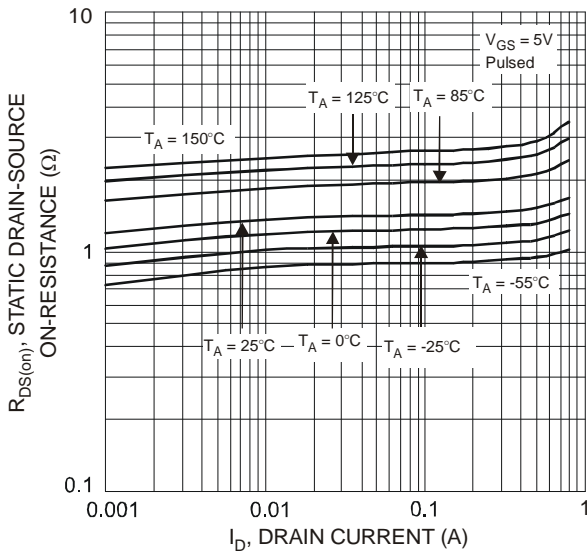
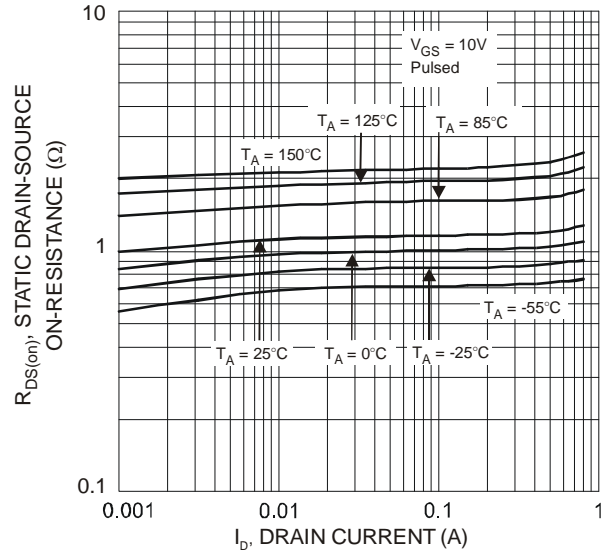
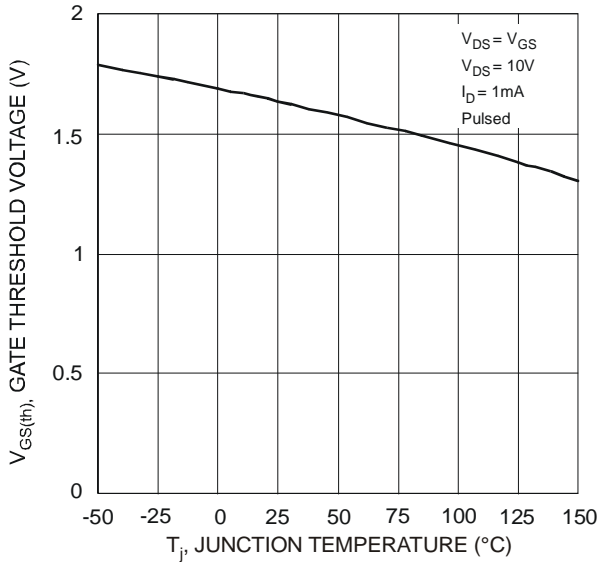
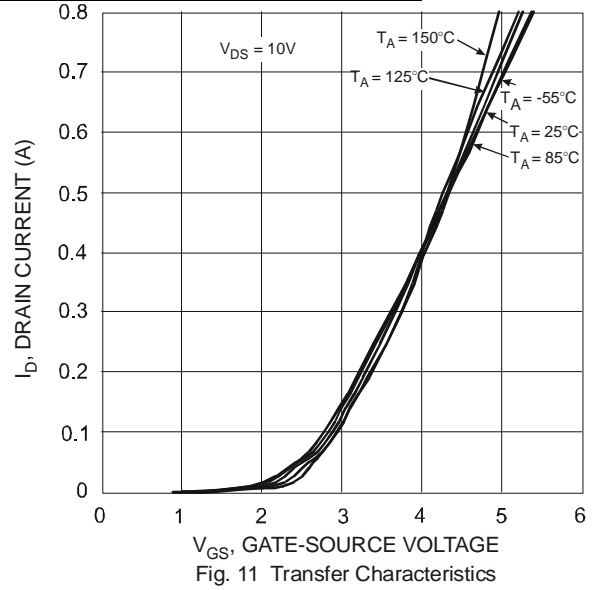
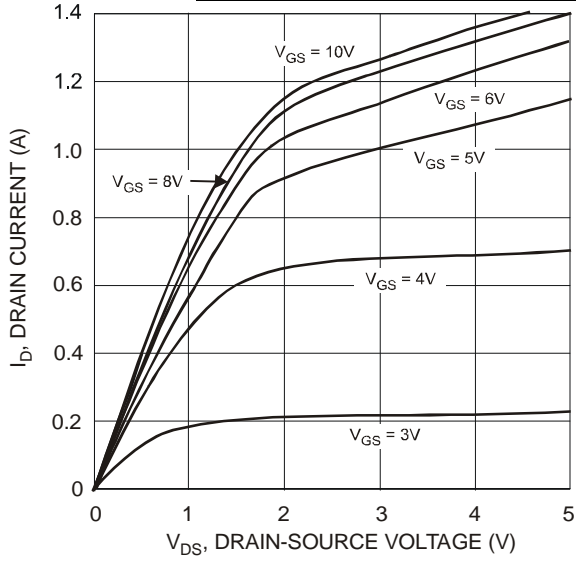


Fig. 9  $h_{FE}$  vs.  $I_C$  @  $V_{CE} = 5\text{V}$

## Typical N-Channel MOSFET (ESD Protected) Characteristics

NEW PRODUCT



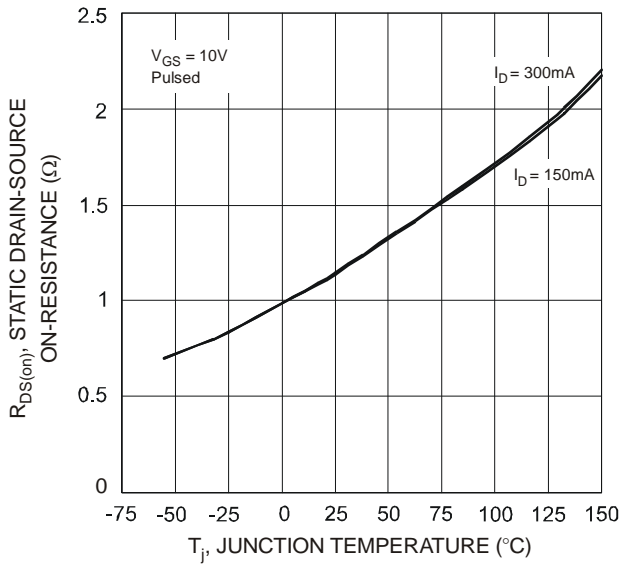


Fig. 16 Static Drain-Source On-State Resistance vs. Junction Temperature

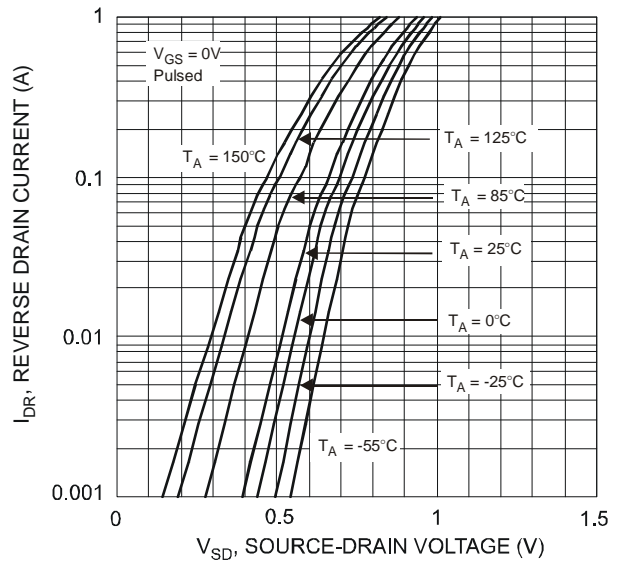


Fig. 17 Reverse Drain Current vs. Source-Drain Voltage

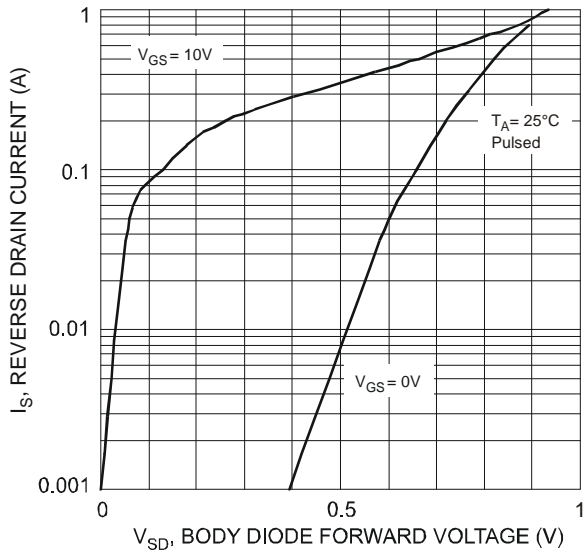


Fig. 18 Reverse Drain Current vs. Source-Drain Voltage

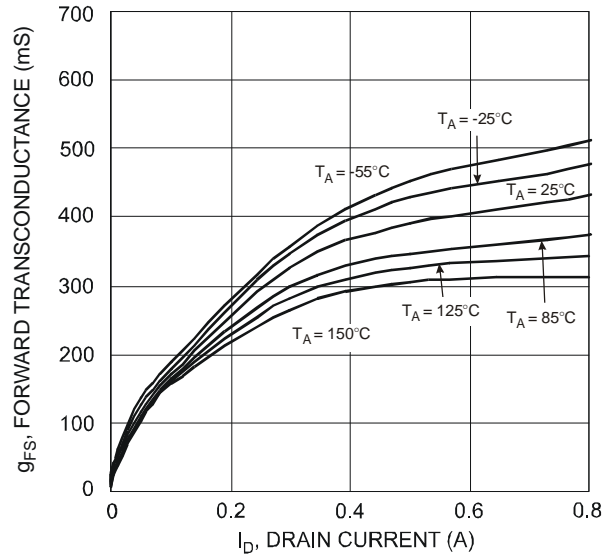


Fig. 19 Forward Transconductance vs. Drain Current ( $V_{DS} > I_D * R_{DS(ON)}$ )

## Application Details

PNP Transistor (DDTB122LU) and ESD Protected N-MOSFET (DMN601TK) integrated as one in LMN400E01 can be used as a discrete entity for general application or as an integrated circuit to function as a Load Switch. When it is used as the latter as shown in Fig. 20, various input voltage sources can be used as long as it does not exceed the maximum ratings of the device. These devices are designed to deliver continuous output load current up to a maximum of 400 mA. The MOSFET Switch draws no current, hence loading of control circuitry is prevented. Care must be taken for higher levels of dissipation while designing for higher load conditions. These devices provide high power and also consume less space. The product mainly helps in optimizing power usage, thereby conserving battery life in a controlled load system like portable battery powered applications. (Please see Fig. 21 for one example of a typical application circuit used in conjunction with a voltage regulator as a part of power management system).

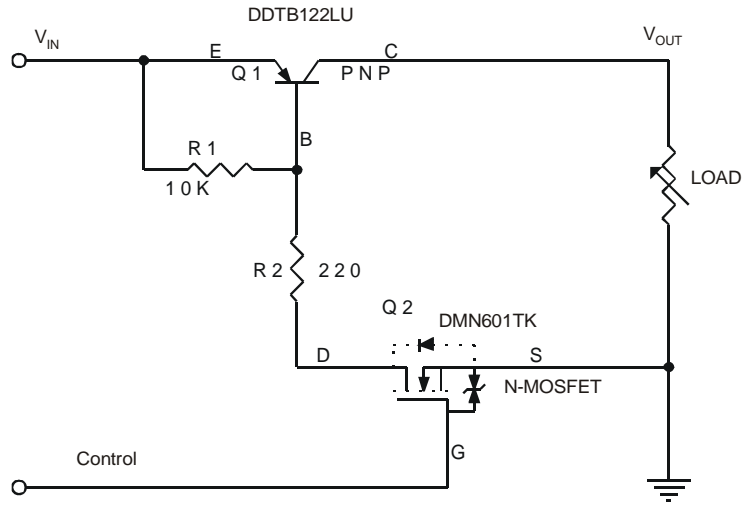


Fig. 20 Circuit Diagram

### Typical Application Circuit

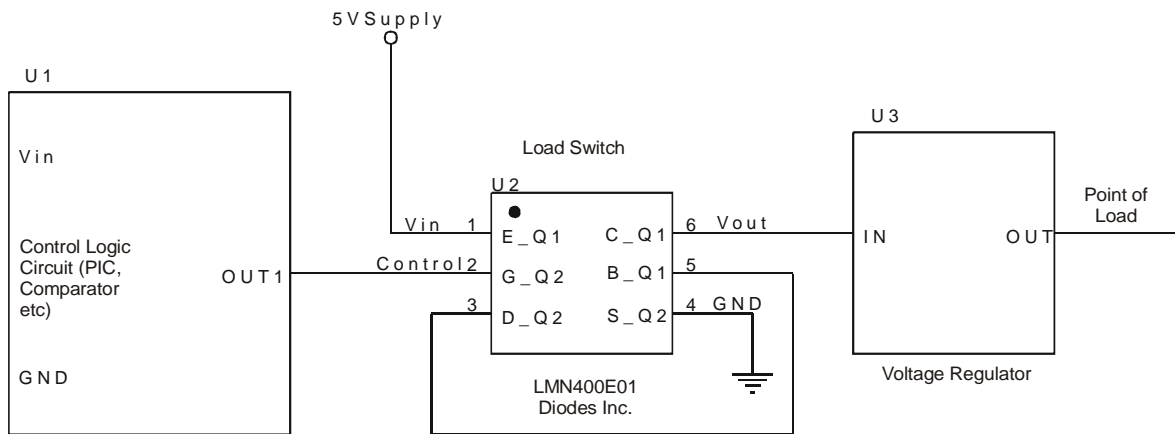


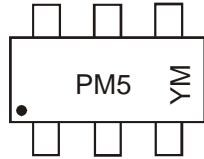
Fig. 21

## Ordering Information (Note 5)

Device	Packaging	Shipping
LMN400E01-7	SOT-363	3000/Tape & Reel

Notes: 5. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

## Marking Information



PM5 = Product Type Marking Code,  
 YM = Date Code Marking  
 Y = Year, e.g., T = 2006  
 M = Month, e.g., 9 = September

Fig. 22

Date Code Key

Year	2006	2007	2008	2009	2010	2011	2012
Code	T	U	V	W	X	Y	Z

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

## Mechanical Details

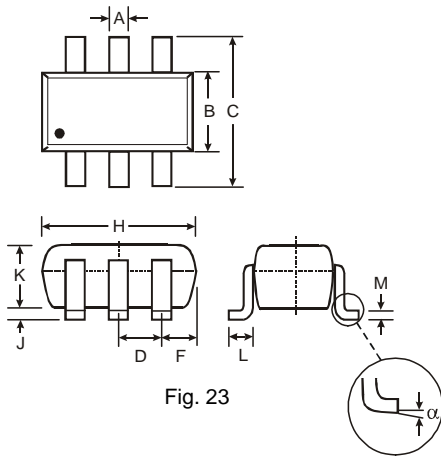


Fig. 23

Fig. 24

SOT-363		
Dim	Min	Max
A	0.10	0.30
B	1.15	1.35
C	2.00	2.20
D	0.65 Nominal	
F	0.30	0.40
H	1.80	2.20
J	-	0.10
K	0.90	1.00
L	0.25	0.40
M	0.10	0.25
$\alpha$	0°	8°
All Dimensions in mm		

## Suggested Pad Layout:

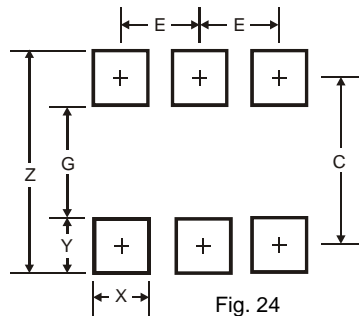


Figure 24 Dimensions	Value (mm)
Z	2.5
G	1.3
X	0.42
Y	0.6
C	1.9
E	0.65

### IMPORTANT NOTICE

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to any product herein. Diodes Incorporated does not assume any liability arising out of the application or use of any product described herein; neither does it convey any license under its patent rights, nor the rights of others. The user of products in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on our website, harmless against all damages.

### LIFE SUPPORT

Diodes Incorporated products are not authorized for use as critical components in life support devices or systems without the expressed written approval of the President of Diodes Incorporated.